

MOSFET – P-Channel, POWERTRENCH®

30 V

FDD6685

General Description

This P-Channel MOSFET is a rugged gate version of onsemi's advanced POWERTRENCH process. It has been optimized for power management applications requiring a wide range of gate drive voltage ratings (4.5 V – 2.5 V).

Features

- -40 A, -30 V
 - ♦ $R_{DS(ON)} = 20\text{ m}\Omega$ @ $V_{GS} = -10\text{ V}$
 - ♦ $R_{DS(ON)} = 30\text{ m}\Omega$ @ $V_{GS} = -4.5\text{ V}$
- Fast Switching Speed
- High Performance Trench Technology for Extremely Low $R_{DS(ON)}$
- High Power and Current Handling Capability
- Qualified to AEC-Q101
- This Device is Pb-Free and are RoHS Compliant

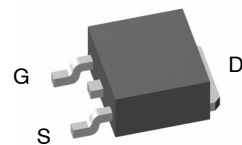
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, Unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 25	V
I_D	Continuous Drain Current	@ $T_C = 25^\circ\text{C}$ (Note 5)	A
		@ $T_A = 25^\circ\text{C}$ (Note 3a)	
		Pulsed, $PW \leq 100\text{ }\mu\text{s}$ (Note 3b)	
P_D	Power Dissipation for Single Operation	(Note 3)	W
		(Note 3a)	
		(Note 3b)	
		(Note 3b)	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ\text{C}$

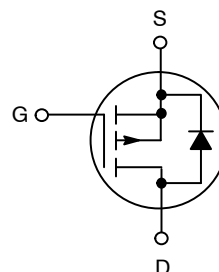
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

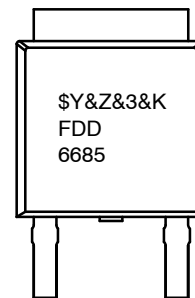
Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 3)	2.9	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 3a)	40	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 3b)	96	$^\circ\text{C/W}$



DPAK3 (TO-252 3 LD)
CASE 369AS



MARKING DIAGRAM



\$Y = onsemi Logo
 &Z = Assembly Plant Code
 &3 = Numeric Date Code
 &K = Lot Code
 FDD6685 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

FDD6685

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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DRAIN-SOURCE AVALANCHE RATINGS (NOTE 4)

E_{AS}	Single Pulse Drain-Source Avalanche Energy	$I_D = -11\text{ A}$	–	42	–	mJ
I_{AS}	Maximum Drain-Source Avalanche Current		–	–11	–	A

OFF CHARACTERISTICS

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	–30	–	–	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250\text{ }\mu\text{A}$, Referenced to 25°C	–	–24	–	mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24\text{ V}, V_{GS} = 0\text{ V}$	–	–	–1	μA
I_{GSS}	Gate-Body Leakage	$V_{GS} = \pm 25\text{ V}, V_{DS} = 0\text{ V}$	–	–	± 100	nA

ON CHARACTERISTICS

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	–1	–1.8	–3	V
$\Delta V_{GS(th)} / \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250\text{ }\mu\text{A}$, Referenced to 25°C	–	5	–	mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -11\text{ A}$ $V_{GS} = -4.5\text{ V}, I_D = -9\text{ A}$ $V_{GS} = -10\text{ V}, I_D = -11\text{ A}, T_J = 125^\circ\text{C}$	–	14 21 20	20 30	m Ω
$I_{D(on)}$	On-State Drain Current	$V_{GS} = -10\text{ V}, V_{DS} = -5\text{ V}$	–20	–	–	A
g_{FS}	Forward Transconductance	$V_{DS} = -5\text{ V}, I_D = -11\text{ A}$	–	26	–	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = -15\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	–	1715	–	pF
C_{oss}	Output Capacitance		–	440	–	pF
C_{rss}	Reverse Transfer Capacitance			225	–	pF
R_G	Gate Resistance	$V_{GS} = 15\text{ mV}, f = 1.0\text{ MHz}$	–	3.6	–	Ω

SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -15\text{ V}, I_D = -1\text{ A}, V_{GS} = -10\text{ V}, R_{GEN} = 6\text{ }\Omega$	–	17	31	ns
t_r	Turn-On Rise Time		–	11	21	ns
$t_{d(off)}$	Turn-Off Delay Time			43	68	ns
t_f	Turn-Off Fall Time		–	21	34	ns
Q_g	Total Gate Charge	$V_{DS} = -15\text{ V}, I_D = -11\text{ A}, V_{GS} = -5\text{ V}$	–	17	24	nC
Q_{gs}	Gate-Source Charge		–	9	–	nC
Q_{gd}	Gate-Drain Charge			4	–	nC

DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -3.2\text{ A}$ (Note 4)	–	–0.8	–1.2	V
T_{rr}	Diode Reverse Recovery Time	$I_F = -11\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$	–	26	–	ns
Q_{rr}	Diode Reverse Recovery Charge		–	13	–	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

FDD6685

NOTES:

1. This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry.
2. All **onsemi** products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.
3. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



- a) $R_{\theta JA} = 40^{\circ}\text{C/W}$ when mounted on
■ 1 in² pad of 2 oz copper



- b) $R_{\theta JA} = 96^{\circ}\text{C/W}$ when mounted on
■ a minimum pad

4. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%
5. Maximum current is calculated as:

$$\sqrt{\frac{P_D}{R_{DS(ON)}}}$$

where P_D is maximum power dissipation at $T_C = 25^{\circ}\text{C}$ and $R_{DS(on)}$ is at $T_{J(max)}$ and $V_{GS} = 10\text{ V}$.

6. Starting $T_J = 25^{\circ}\text{C}$, $L = 0.69\text{ mH}$, $I_{AS} = -11\text{ A}$

TYPICAL CHARACTERISTICS

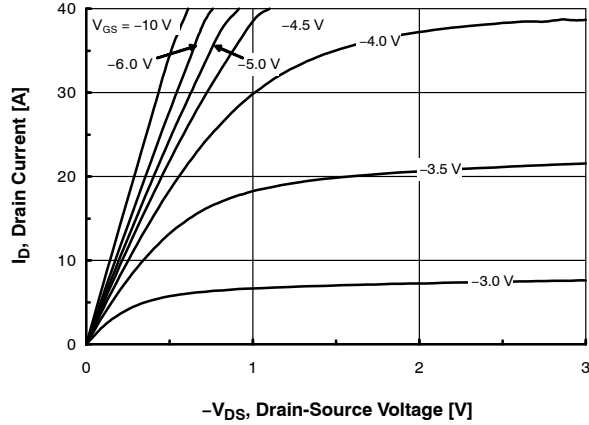


Figure 1. On-Region Characteristics

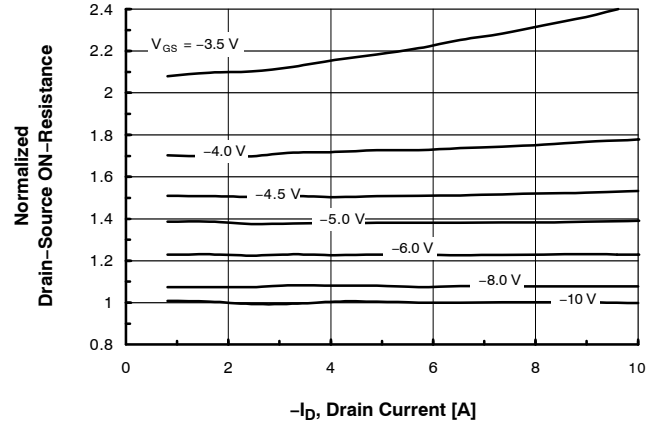


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

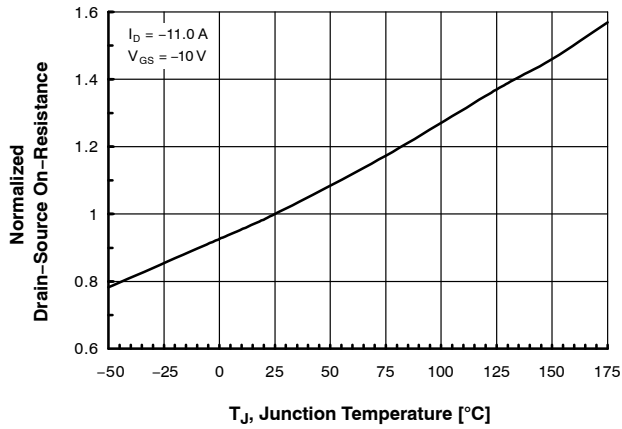


Figure 3. On-Resistance Variation with Temperature

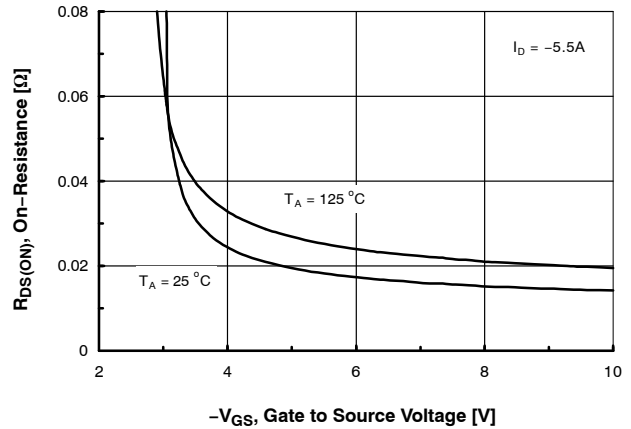


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

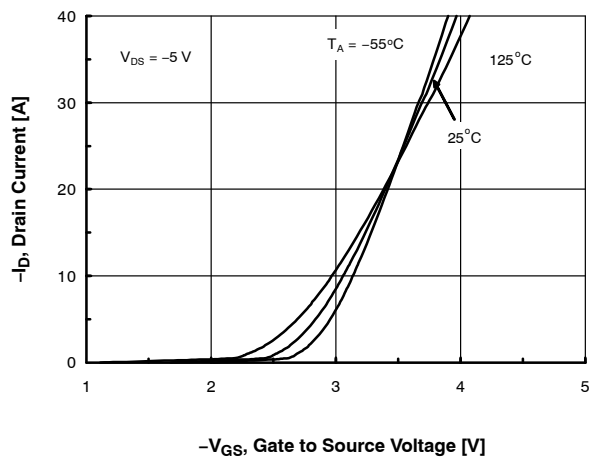


Figure 5. Transfer Characteristics

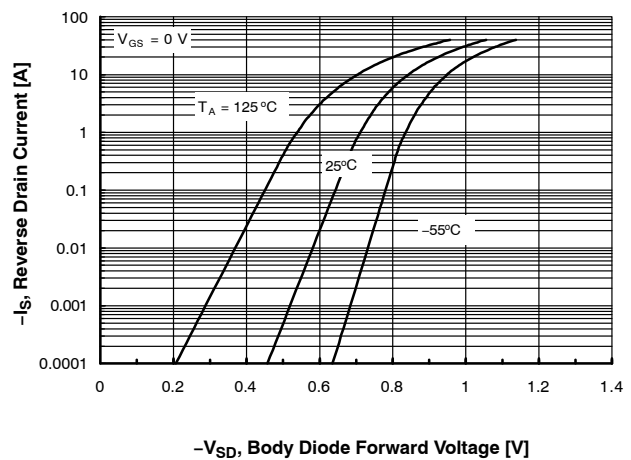


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

TYPICAL CHARACTERISTICS (continued)

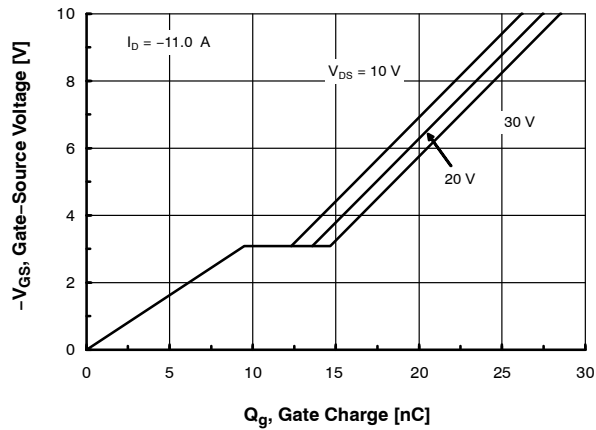


Figure 7. Gate Charge Characteristics

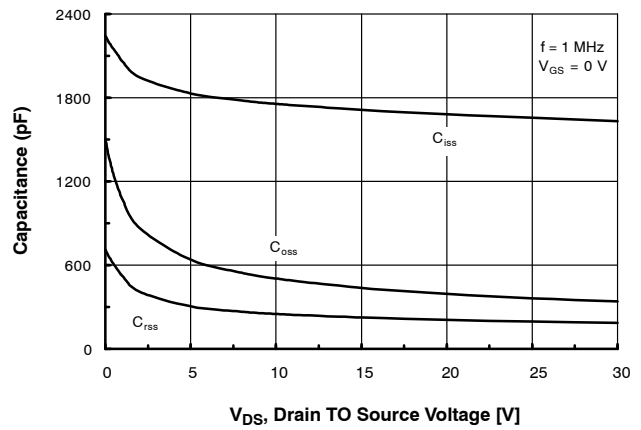


Figure 8. Capacitance Characteristics

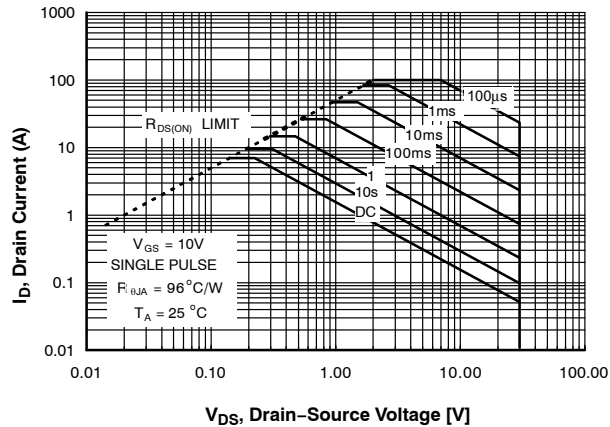


Figure 9. Maximum Safe Operating Area

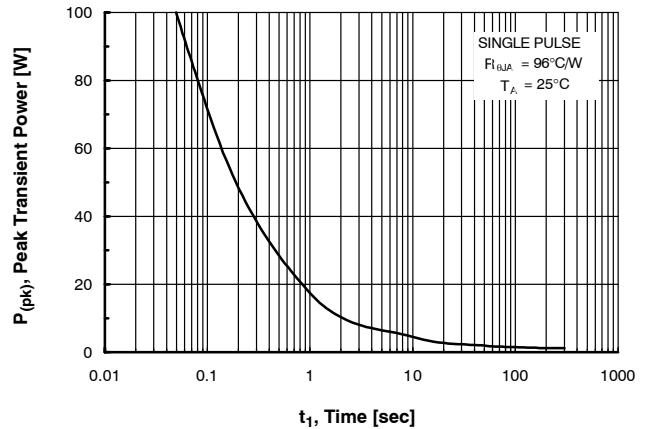


Figure 10. Single Pulse Minimum Power Dissipation

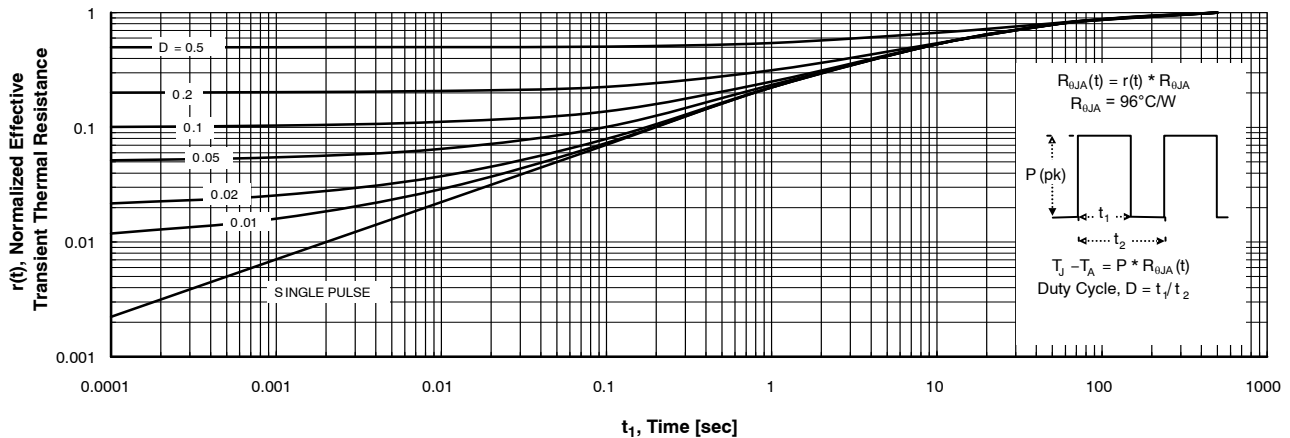


Figure 11. Transient Thermal Response Curve

NOTES:

7. Thermal characterization performed using the conditions described in Note 3b.
8. Transient thermal response will change depending on the circuit board design.

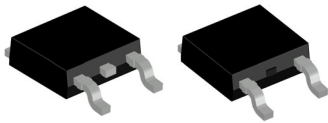
FDD6685

PACKAGE MARKING AND ORDERING INFORMATION

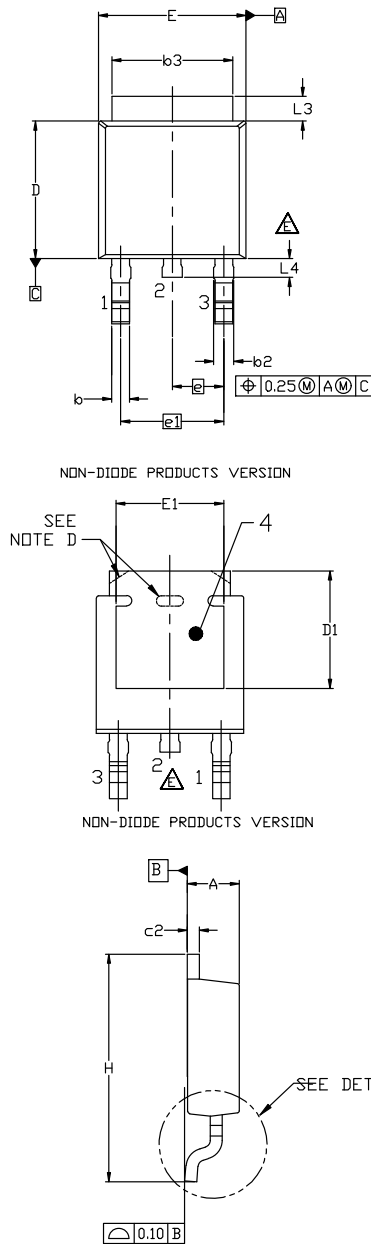
Part Number	Device	Reel Size	Tape Width	Shipping [†]
FDD6685	FDD6685	13"	16 mm	2,500 Tape & Reels

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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DPAK3 6.10x6.54x2.29, 4.57P
CASE 369AS
ISSUE B

DATE 20 DEC 2023



NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE F, VARIATION AA.

B) ALL DIMENSIONS ARE IN MILLIMETERS.

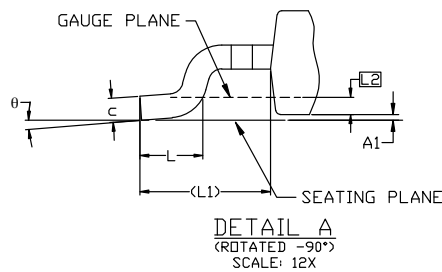
C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2018.

D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION.

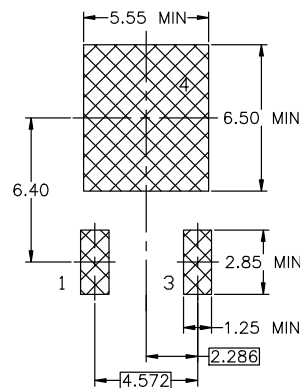
E) FOR DIODE PRODUCTS, L4 IS 0.25 MM MAX PLASTIC BODY STUB WITHOUT CENTER LEAD.

F) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

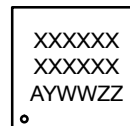
G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD TD228P991X239-3N.



DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	2.18	2.29	2.39
A1	0.00	—	0.127
b	0.64	0.77	0.89
b2	0.76	0.95	1.14
b3	5.21	5.34	5.46
c	0.45	0.53	0.61
c2	0.45	0.52	0.58
D	5.97	6.10	6.22
D1	5.21	---	---
E	6.35	6.54	6.73
E1	4.32	---	---
e	2.286 BSC		
e1	4.572 BSC		
H	9.40	9.91	10.41
L	1.40	1.59	1.78
L1	2.90 REF		
L2	0.51 BSC		
L3	0.89	1.08	1.27
L4	---	---	1.02
θ	0°	---	10°


LAND PATTERN RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*


*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Assembly Lot Code

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